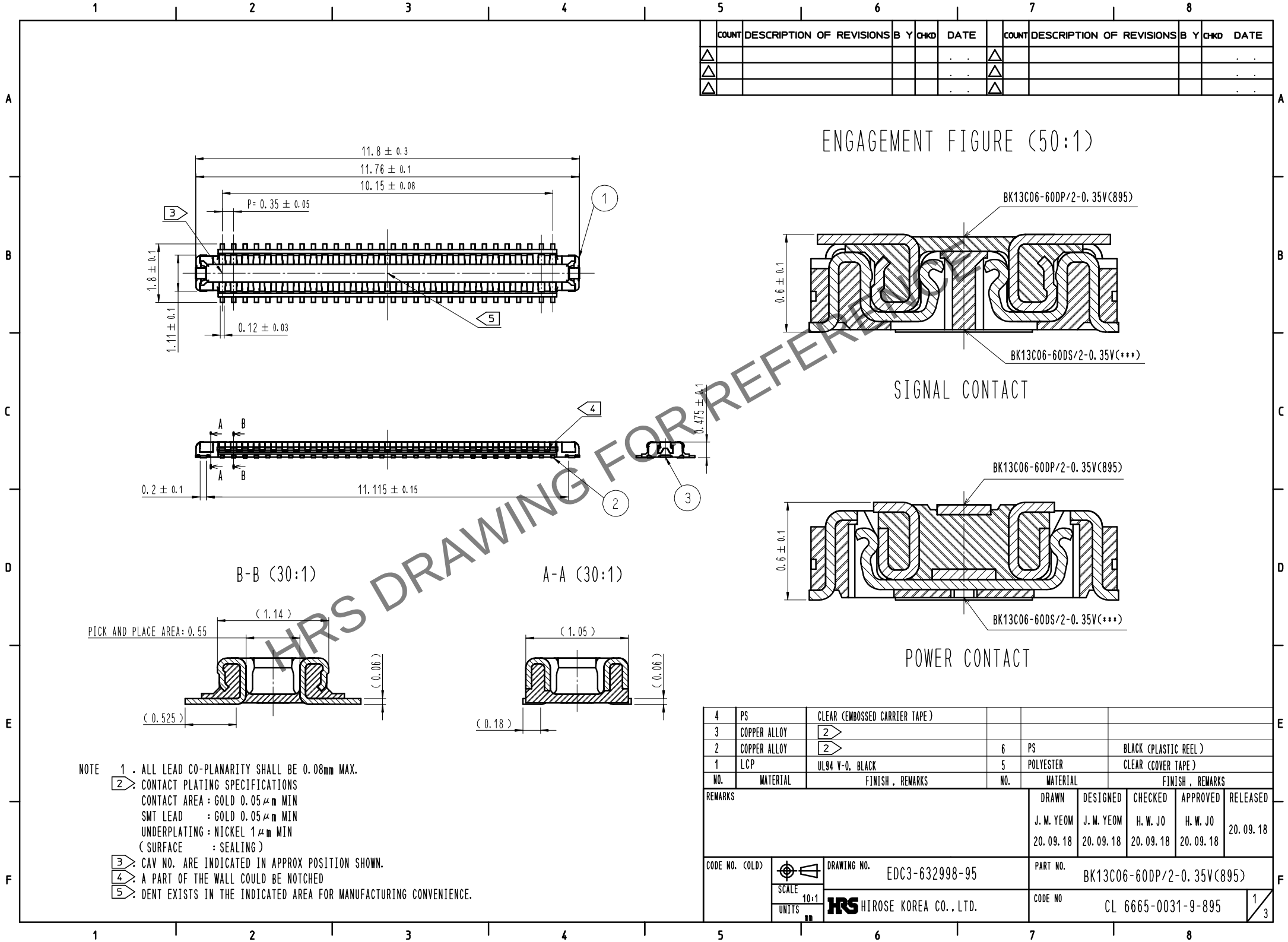
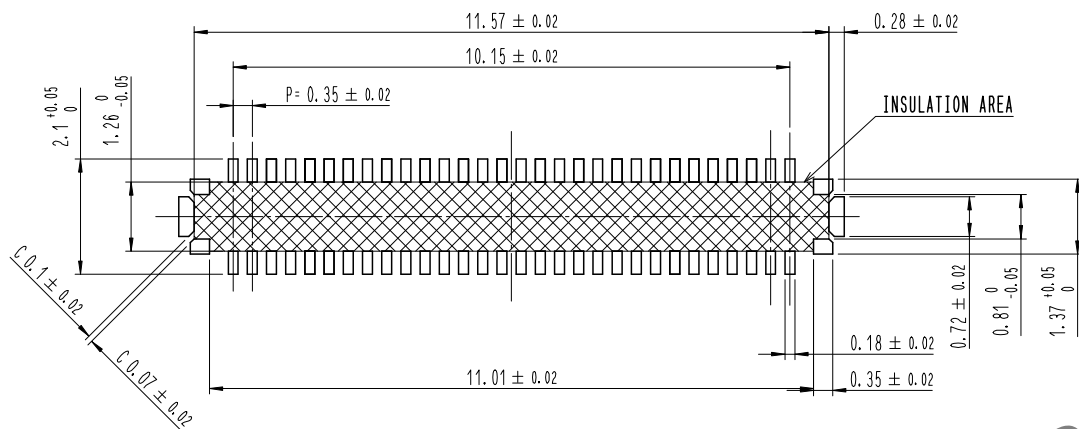


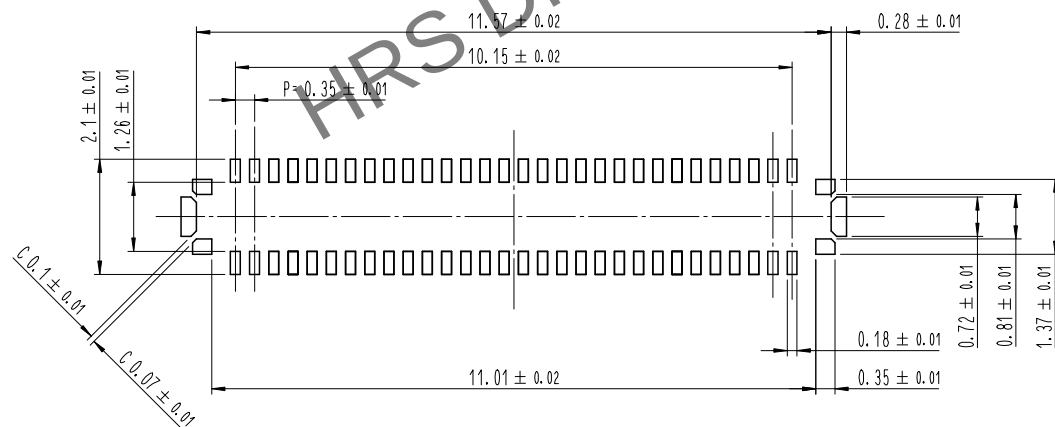


7 RECOMMENDED PCB LAYOUT

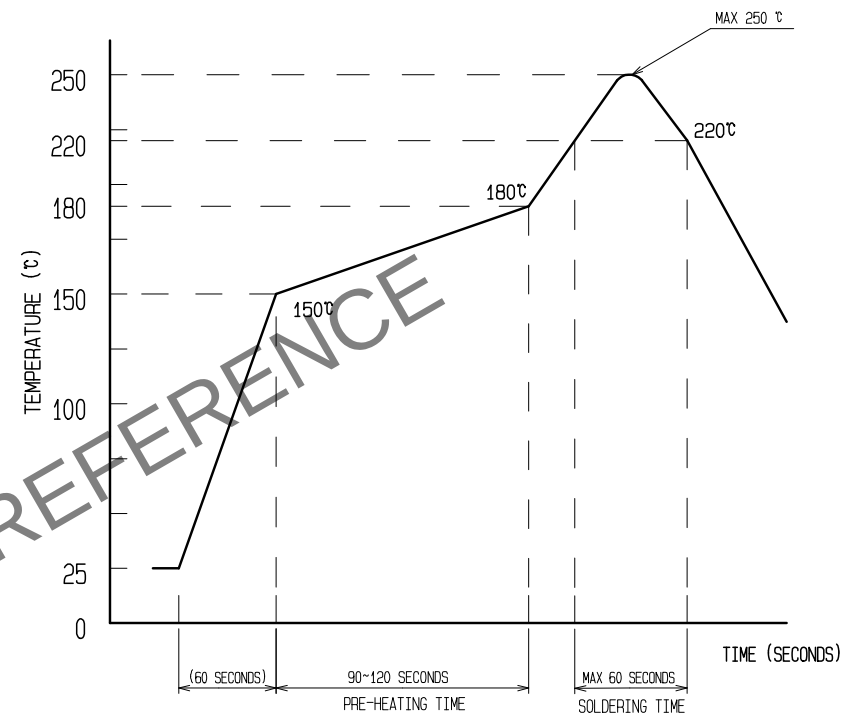


RECOMMENDED METAL MASK DIMENSIONS

METAL MASK THICKNESS : 80 μm



6 RECOMMENDED REFLOW TEMPERATURE PROFILE
USING LEAD-FREE SOLDER PASTE.



REFLOW METHOD : N₂ REFLOW
NUMBER OF REFLOW CYCLES : 2 CYCLES MAX.
1) REFLOW TIME
DURATION ABOVE 220°C: 60 SEC MAX.
(PEAK TEMPERATURE : 250°C MAX)
2) PRE-HEAT TIME
PRE-HEAT TEMPERATURE(MIN): 150°C
PRE-HEAT TEMPERATURE(MAX): 180°C
PRE-HEAT TIME: 90-120 SEC.

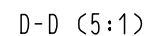
6. THIS TEMPERATURE PROFILE IS PER THE CONDITIONS SHOWN ABOVE. ADDITIONAL FACTORS SUCH AS SOLDER PASTE TYPE, PCB SIZE AND OTHER MOUNTED COMPONENTS COULD AFFECT THE PROFILE. THEREFORE, A THOROUGH EVALUATION OF MOUNTING CONDITION IS REQUIRED PRIOR TO PRODUCTION. TEMPERATURE IS MEASURED AT CONTACT LEAD.

7. PLEASE CONTACT US IN CASE YOU WILL MAKE DIFFERENT SETTINGS FROM OUR RECOMMENDATION.

8. THIS PRODUCT SATISFIES HALOGEN FREE REQUIREMENTS DEFINED AS 900ppm MAXIMUM CHLORINE, 900ppm MAXIMUM BROMINE, AND 1500ppm MAXIMUM TOTAL OF CHLORINE AND BROMINE.

9. THIS PRODUCT COMPLY WITH RoHS.

	DRAWING NO. EDC3-632998-95		PART NO. BK13C06-60DP/2-0.35V(895)	
	SCALE 10:1 UNITS 	 HIROSE KOREA CO., LTD.	CODE NO CL 6665-0031-9-895	$\frac{2}{3}$

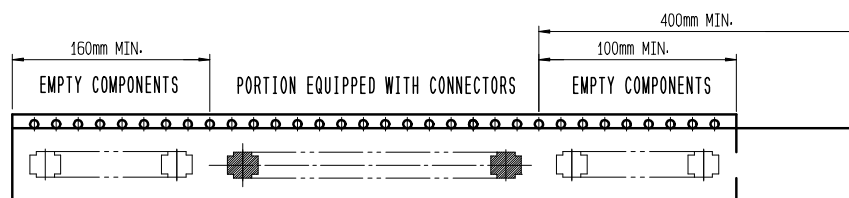
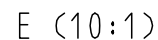


STYLE AND DIMENSION OF REEL (FREE)



C-C (5:1)

DIRECTION OF UNREELING



TRAILER

LEADER

12 TAPING(FREE)

	DRAWING NO. EDC3-632998-95		PART NO. BK13C06-60DP/2-0.35V(895)	
	SCALE 10:1 UNITS  HIROSE KOREA CO., LTD.		CODE NO CL 6665-0031-9-895 $\frac{3}{3}$	